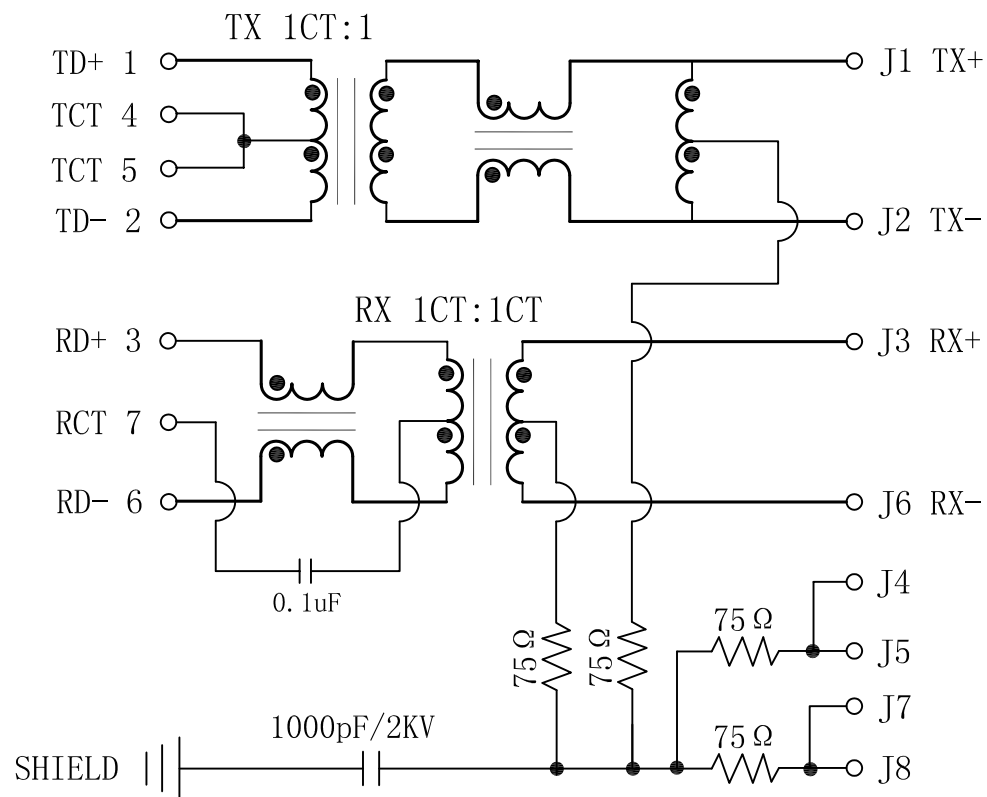


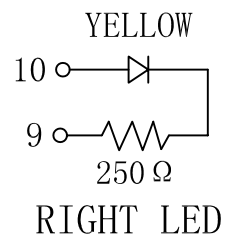
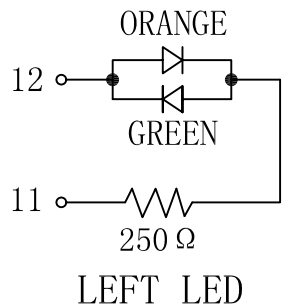
# Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2010/11/03	



## Electrical Specifications @25°C

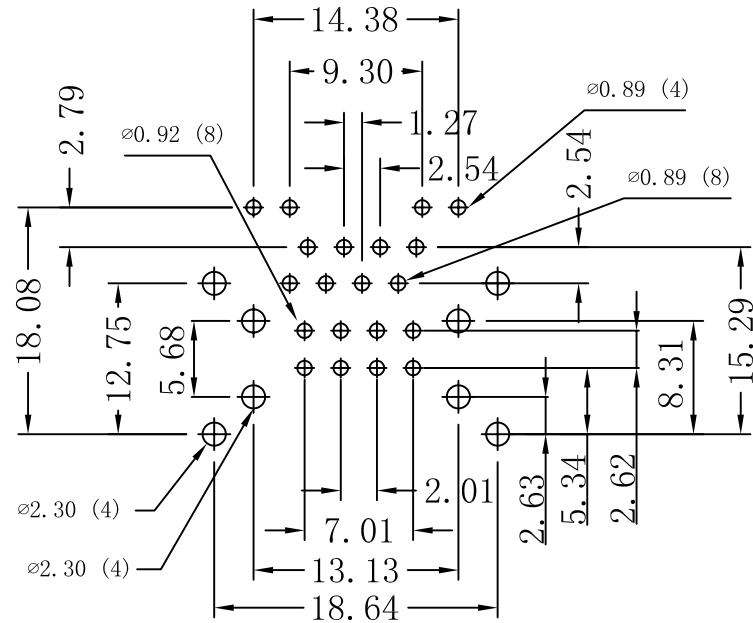
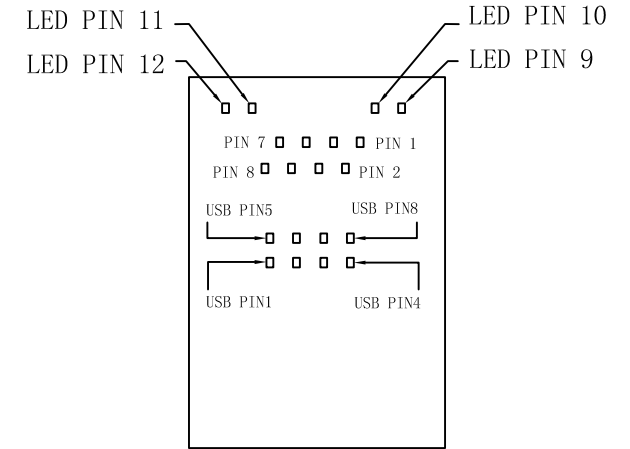
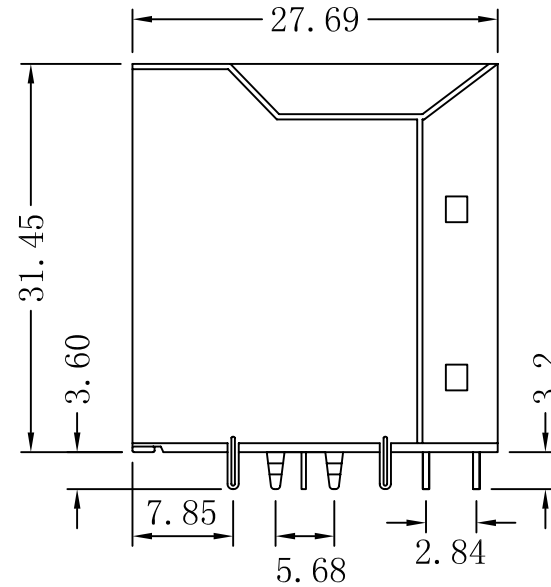
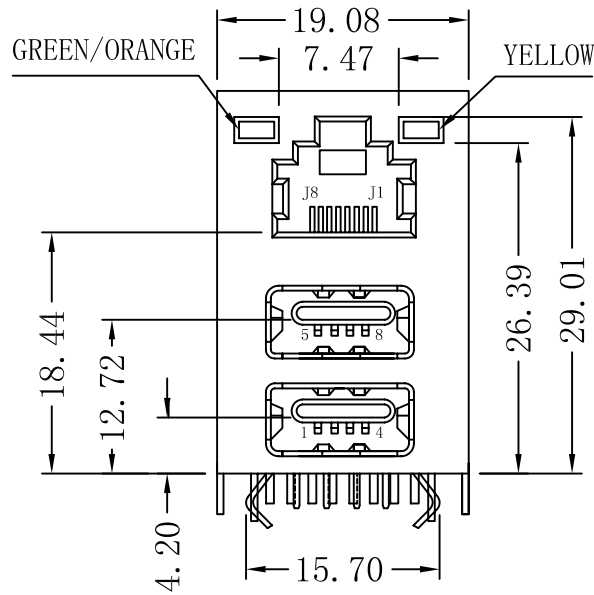
- Turns Ratio:  
TX=1CT:1 ±5%  
RX=1CT:1CT ±5%
- OCL: (100KHz, 100mVRMS, 8mA, DC BIAS)  
350uH MIN
- Hipot (Isolation Voltage): 1500Vrms
- Insertion Loss:  
-1.0dB MAX @ 100KHz TO 100MHz
- Return Loss:  
-18dB MIN @ 1MHz TO 30MHz  
-16dB MIN @ 30MHz TO 60MHz  
-12dB MIN @ 60MHz TO 80MHz
- Cross Talk:  
-40dB MIN @ 1MHz TO 10MHz  
-35dB MIN @ 32MHz TO 60MHz  
-30dB MIN @ 60MHz TO 100MHz
- Common Mode Rejection:  
-30dB MIN @ 1MHz TO 50MHz  
-20dB MIN @ 50MHz TO 100MHz
- Operating Temperature: -40~+85°C



X:X	±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.20	CHKD:	Title: RJ45 10/100 BASE-TX JACK/ Dual USB Combo	
X:XXX	±0.10	DR: TOM	PART NO.: LPJU5402B79NL	
ANGLES	±1°	UNIT: mm		
	SCALE: 2/1	SHEET: 1/2	REV: A	DWG NO.: TRC10110308

# Mechanical :

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2010/11/03	



SUGGESTED PCB LAYOUT (TOP VIEW)



## NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
2. Meets IEEE 802.3 specification
3. Connector Materials:  
 Housing: Thermoplastic UL94V-0  
 Contact/Shield: Copper alloy  
 Shield plating: Nickel  
 Contact plating: Gold 6 micro-inches min. In contact area.  
 USB Contact plating: Gold flash.
4. Wave solder tip temperature: 265°C Max  
 Wave solder tip temperature time: 5 Sec Max

X:X	±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.20	CHKD:	Title: RJ45 10/100 BASE-TX JACK/ Dual USB Combo	
X:XXX	±0.10	DR: TOM	PART NO. : LPJU5402B79NL	
ANGLES	±1°	UNIT: mm		
	SCALE: 2/1	SHEET: 2/2	REV: A	DWG NO. : TRC10110308